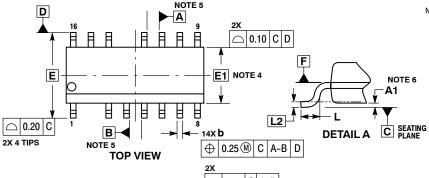


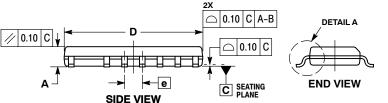
SCALE 1:1

SOIC-16 NB MISSING PINS 2 AND 13

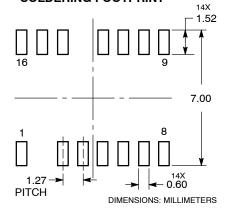
CASE 751DU ISSUE O

DATE 18 OCT 2013





RECOMMENDED SOLDERING FOOTPRINT

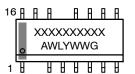


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.25 mm PER SIDE. DIMEN-SIONS D AND E ARE DETERMINED AT DATUM F.
- DIMENSIONS A AND B ARE TO BE DETERMINED AT DATUM F.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

| | MILLIMETERS | | |
|-----|-------------|-------|--|
| DIM | MIN | MAX | |
| Α | 1.35 | 1.75 | |
| A1 | 0.10 0.25 | | |
| b | 0.35 | 0.49 | |
| С | 0.17 | 0.25 | |
| D | 9.80 | 10.00 | |
| Е | 6.00 BSC | | |
| E1 | 3.90 BSC | | |
| е | 1.27 BSC | | |
| L | 0.40 | 1.27 | |
| L2 | 0.203 BSC | | |

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code

= Assembly Location Α

WL = Wafer Lot Υ = Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

| DOCUMENT NUMBER: | 98AON77502F | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. | |
|------------------|----------------------------------|---|-------------|
| DESCRIPTION: | SOIC-16 NB MISSING PINS 2 AND 13 | | PAGE 1 OF 1 |

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries, onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.